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RENESAS TECHNICAL UPDATE

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Product Category	MPU/MCU		Document No.	TN-RL*-A0110A/E	Rev.	1.00
Title	Correction for Incorrect Description Notice RL78/L13 Descriptions in the User's Manual: Hardware Rev. 2.21 Changed		Information Category	Technical Notification		
Applicable Product	RL78/L13 Group	Lot No. All lots	Reference Document	RL78/L13 User's Manual: Hardware Rev. 2.21 R01UH0382EJ0221 (Sep. 2022)		

This document describes misstatements found in the RL78/L13 User's Manual: Hardware Rev. 2.21 (R01UH0382EJ0221).

Corrections

Applicable Item	Applicable Page	Contents
8.3.5 Real-time clock control register 1 (RTCC1)	Page 398	Incorrect descriptions revised
Figure 8-20. Procedure for Reading Real-time Clock 2	Page 413	Incorrect descriptions revised
Figure 8-21. Procedure for Writing Real-time Clock 2 Counter	Page 414	Incorrect descriptions revised
32.3.2 Supply current characteristics	Page 1012 to Page 1015	Incorrect descriptions revised
33.3.2 Supply current characteristics	Page 1076 to Page 1079	Incorrect descriptions revised

Document Improvement

The above corrections will be made for the next revision of the User's Manual: Hardware.

Corrections in the User's Manual: Hardware

No.	Corrections and Applicable Items			Pages in this document for corrections
	Document No.	English	R01UH0382EJ0221	
1	8.3.5 Real-time clock control register 1 (RTCC1)		Page 398	Page 3
2	Figure 8-20. Procedure for Reading Real-time Clock 2		Page 413	Page 4
3	Figure 8-21. Procedure for Writing Real-time Clock 2 Counter		Page 414	Page 4
4	32.3.2 Supply current characteristics		Page 1012 to Page 1015	Page 5 to Page 7
5	33.3.2 Supply current characteristics		Page 1076 to Page 1079	Page 8 to Page 10

Incorrect: Bold with underline; Correct: Gray hatched

Revision History

RL78/L13 Correction for incorrect description notice

Document Number	Issue Date	Description
TN-RL*-A0110A/E	Jan. 19, 2023	First edition issued Corrections No.1 to No.5 revised (this document)

1. 8.3.5 Real-time clock control register 1 (RTCC1) (p.398)

Incorrect:

Figure 8-6. Format of Real-time Clock Control Register 1 (RTCC1) (3/3)

RWST	Wait status flag of real-time clock 2
0	Counter is operating.
1	Mode to read or write counter value.
This status flag indicates whether the setting of the RWAIT bit is valid. Before reading or writing the counter value, confirm that the value of this flag is 1. Even if the RWAIT bit is set to 0, the RWST bit is not set to 0 while writing to the counter. After writing is completed, the RWST bit is set to 0.	

RWAIT	Wait control of real-time clock 2
0	Sets counter operation.
1	Stops SEC to YEAR counters. Mode to read or write counter value.
This bit controls the operation of the counter. Be sure to write “1” to it to read or write the counter value. As the counter (16-bit) is continuing to run, complete reading or writing within one second and turn back to 0. When RWAIT = 1, it takes up to one cycle of f_{RTC} until the counter value can be read or written (RWST = 1).Notes1, 2 When the internal counter (16-bit) overflowed while RWAIT = 1, it keeps the event of overflow until RWAIT = 0, then counts up. However, when it wrote a value to second count register, it will not keep the overflow event.	

Correct:

Figure 8-6. Format of Real-time Clock Control Register 1 (RTCC1) (3/3)

RWST	Wait status flag of real-time clock 2
0	Counter is operating.
1	Mode to read or write counter value.
This status flag indicates whether the setting of the RWAIT bit is valid. Before reading or writing the counter value, confirm that the value of this flag is 1. Even if the RWAIT bit is set to 0, the RWST bit is not set to 0 while writing to the counter. After writing is completed, the RWST bit is set to 0.	

RWAIT	Wait control of real-time clock 2
0	Sets counter operation.
1	Stops SEC to YEAR counters. Mode to read or write counter value.
This bit controls the operation of the counter. Be sure to write “1” to it to read or write the counter value. As the counter (16-bit) is continuing to run, complete reading or writing within one second and turn back to 0. When reading or writing to the counter is required while generation of the alarm interrupt is enabled, first set the CT2 to CT0 bits to 010B (generating the constant-period interrupt once per 1 second). Then, complete the processing from setting the RWAIT bit to 1 to setting it to 0 before generation of the next constant-period interrupt. When RWAIT = 1, it takes up to one cycle of f_{RTC} until the counter value can be read or written (RWST = 1).Notes1, 2 When the internal counter (16-bit) overflowed while RWAIT = 1, it keeps the event of overflow until RWAIT = 0, then counts up. However, when it wrote a value to second count register, it will not keep the overflow event.	

2. Figure 8-20. Procedure for Reading Real-time Clock 2 (p.413)

Incorrect:

Notes 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

2. Be sure to confirm that RWST = 0 before shifting to STOP mode.

Caution Complete setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be read.

Correct:

Notes 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

2. Be sure to confirm that RWST = 0 before shifting to STOP mode.

Caution Complete setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second. When reading to the counter is required while generation of the alarm interrupt is enabled, first set the CT2 to CT0 bits to 010B (generating the constant-period interrupt once per 1 second). Then, complete the processing from setting the RWAIT bit to 1 to setting it to 0 before generation of the next constant-period interrupt.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be read.

3. Figure 8-21. Procedure for Writing Real-time Clock 2 Counter (p.414)

Incorrect:

Notes 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

2. Be sure to confirm that RWST = 0 before shifting to STOP mode.

Cautions 1. Complete setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second.

2. When changing the values of the SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR registers while the counter operates (RTCE = 1), rewrite the values of the MIN register after disabling interrupt servicing INTRTC by using the interrupt mask flag register. Furthermore, clear the WAFG, RIFG, and RTCIF flags after rewriting the MIN register.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be read in any sequence. All the registers do not have to be set and only some registers may be written.

Correct:

Notes 1. When the counter is stopped (RTCE = 0), RWST is not set to 1.

2. Be sure to confirm that RWST = 0 before shifting to STOP mode.

Cautions 1. Complete setting the RWAIT bit to 1 to clearing the RWAIT bit to 0 within 1 second. When writing to the counter is required while generation of the alarm interrupt is enabled, first set the CT2 to CT0 bits to 010B (generating the constant-period interrupt once per 1 second). Then, complete the processing from setting the RWAIT bit to 1 to setting it to 0 before generation of the next constant-period interrupt.

2. When changing the values of the SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR registers while the counter operates (RTCE = 1), rewrite the values of the MIN register after disabling interrupt servicing INTRTC by using the interrupt mask flag register. Furthermore, clear the WAFG, RIFG, and RTCIF flags after rewriting the MIN register.

Remark SEC, MIN, HOUR, WEEK, DAY, MONTH, and YEAR may be written in any sequence. All the registers do not have to be set and only some registers may be written.

4. 32.3.2 Supply current characteristics (p.1012 to p.1015)

Incorrect:

32.3.2 Supply current characteristics

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD1}	Operating mode	HS (high-speed main) mode[Note 5]	f_{HOCO} = 48 MHz[Note 3], f_{IH} = 24 MHz[Note 3]	Basic operation	V_{DD} = 5.0 V		2.0		mA
						V_{DD} = 3.0 V		2.0		mA
					Normal operation	V_{DD} = 5.0 V		3.8	6.5	mA
						V_{DD} = 3.0 V		3.8	6.5	mA
				f_{SUB} = 32.768 kHz[Note 4], T_A = +85°C	Normal operation	Square wave input		4.7	12.0	µA
						Resonator connection		5.2	12.0	µA

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. **The values below the MAX. column include the peripheral operation current.** However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator and subsystem clock are stopped.

3. When high-speed system clock and subsystem clock are stopped.

4. When high-speed on-chip oscillator and high-speed system clock are stopped. When setting ultra-low power consumption oscillation (AMPHS1 = 1). **The current flowing into the LCD controller/driver, 16-bit timer KB20, real-time clock 2, 12-bit interval timer, and watchdog timer is not included.**

5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz
2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz
LV (low-voltage main) mode: 1.6 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 4 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

Correct:

32.3.2 Supply current characteristics

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD1}	Operating mode	HS (high-speed main) mode[Note 5]	f_{HOCO} = 48 MHz[Note 3], f_{IH} = 24 MHz[Note 3]	Basic operation	V_{DD} = 5.0 V		2.0		mA
						V_{DD} = 3.0 V		2.0		mA
					Normal operation	V_{DD} = 5.0 V		3.8	6.5	mA
						V_{DD} = 3.0 V		3.8	6.5	mA
				f_{SUB} = 32.768 kHz[Note 4], T_A = +85°C	Normal operation	Square wave input		4.7	12.0	µA
						Resonator connection		5.2	12.0	µA

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The following points apply in the HS (high-speed main), LS (low-speed main), and LV (low-voltage main) modes.

- The currents in the “TYP.” column do not include the operating currents of the peripheral modules.
- The currents in the “MAX.” column include the operating currents of the peripheral modules, except for those flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, and on-chip pull-up/pull-down resistors, and those flowing while the data flash memory is being rewritten.

In the subsystem clock operation, the currents in both the “TYP.” and “MAX.” columns do not include the operating currents of the peripheral modules. However, in HALT mode, including the current flowing into the real-time clock 2.

2. When high-speed on-chip oscillator and subsystem clock are stopped.

3. When high-speed system clock and subsystem clock are stopped.

4. When high-speed on-chip oscillator and high-speed system clock are stopped. When setting ultra-low power consumption oscillation (AMPHS1 = 1).

5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz
2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz
LV (low-voltage main) mode: 1.6 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 4 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS (high-speed main) mode [Note 7]	f_{HOCO} = 48 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.71	1.95	mA
					V_{DD} = 3.0 V		0.71	1.95	
				f_{HOCO} = 24 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.49	1.64	mA
					V_{DD} = 3.0 V		0.49	1.64	
				f_{HOCO} = 16 MHz[Note 4], f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		0.43	1.11	mA
					V_{DD} = 3.0 V		0.43	1.11	
			LS (low-speed main) mode [Note 7]	f_{HOCO} = 8 MHz[Note 4], f_{IH} = 8 MHz[Note 4]	V_{DD} = 3.0 V		280	770	μA
					V_{DD} = 2.0 V		280	770	
			LV (low-voltage main) mode[Note 7]	f_{HOCO} = 4 MHz[Note 4], f_{IH} = 4 MHz[Note 4]	V_{DD} = 3.0 V		430	700	μA
					V_{DD} = 2.0 V		430	700	
			HS (high-speed main) mode [Note 7]	f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.31	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.29	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.26	0.86	mA
					Resonator connection		0.45	1.15	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.25	0.86	mA
					Resonator connection		0.44	1.15	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.20	0.63	mA
					Resonator connection		0.28	0.71	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.19	0.63	mA
					Resonator connection		0.28	0.71	
			LS (low-speed main) mode[Note 7]	f_{MX} = 8 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
				f_{MX} = 8 MHz[Note 3], V_{DD} = 2.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
	I_{DD3}[Note 6]	STOP mode[Note 8]	T_A = –40°C				0.18	0.52	μA
			T_A = +25°C				0.24	0.52	
			T_A = +50°C				0.33	2.21	
			T_A = +70°C				0.53	3.94	
			T_A = +85°C				0.93	7.95	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed **to** V_{DD} or V_{SS}. **The values below the MAX. column include the peripheral operation current.** However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator and subsystem clock are stopped.

4. When high-speed system clock and subsystem clock are stopped.

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS (high-speed main) mode [Note 6]	f_{HOCO} = 48 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.71	1.95	mA
					V_{DD} = 3.0 V		0.71	1.95	
				f_{HOCO} = 24 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.49	1.64	mA
					V_{DD} = 3.0 V		0.49	1.64	
				f_{HOCO} = 16 MHz[Note 4], f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		0.43	1.11	mA
					V_{DD} = 3.0 V		0.43	1.11	
			LS (low-speed main) mode [Note 6]	f_{HOCO} = 8 MHz[Note 4], f_{IH} = 8 MHz[Note 4]	V_{DD} = 3.0 V		280	770	μA
					V_{DD} = 2.0 V		280	770	
			LV (low-voltage main) mode[Note 6]	f_{HOCO} = 4 MHz[Note 4], f_{IH} = 4 MHz[Note 4]	V_{DD} = 3.0 V		430	700	μA
					V_{DD} = 2.0 V		430	700	
			HS (high-speed main) mode [Note 6]	f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.31	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.29	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.26	0.86	mA
					Resonator connection		0.45	1.15	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.25	0.86	mA
					Resonator connection		0.44	1.15	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.20	0.63	mA
					Resonator connection		0.28	0.71	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.19	0.63	mA
					Resonator connection		0.28	0.71	
			LS (low-speed main) mode[Note 6]	f_{MX} = 8 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
				f_{MX} = 8 MHz[Note 3], V_{DD} = 2.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
	I_{DD3}	STOP mode[Note 7]	T_A = –40°C				0.18	0.52	μA
			T_A = +25°C				0.24	0.52	
			T_A = +50°C				0.33	2.21	
			T_A = +70°C				0.53	3.94	
			T_A = +85°C				0.93	7.95	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed **to** V_{DD} or V_{SS}. The following points apply in the HS (high-speed main), LS (low-speed main), and LV (low-voltage main) modes.

- The currents in the “TYP.” column do not include the operating currents of the peripheral modules.
- The currents in the “MAX.” column include the operating currents of the peripheral modules, except for those flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, and on-chip pull-up/pull-down resistors, and those flowing while the data flash memory is being rewritten.

In the subsystem clock operation, the currents in both the “TYP.” and “MAX.” columns do not include the

5. When high-speed on-chip oscillator and high-speed system clock are stopped. When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1). **The current flowing into the real-time clock 2 is included. However, not including the current flowing into the clock output/buzzer output, 12-bit interval timer, and watchdog timer.**

6. Not including the current flowing into the real-time clock 2, clock output/buzzer output, 12-bit interval timer, and watchdog timer.

7. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz
2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz
LV (low-voltage main) mode: 1.6 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 4 MHz

8. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is T_A = 25°C

operating currents of the peripheral modules. However, in HALT mode, including the current flowing into the real-time clock 2.

In the STOP mode, the currents in both the “TYP.” and “MAX.” columns do not include the operating currents of the peripheral modules.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator and subsystem clock are stopped.

4. When high-speed system clock and subsystem clock are stopped.

5. When high-speed on-chip oscillator and high-speed system clock are stopped. When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1).

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz
2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz
LV (low-voltage main) mode: 1.6 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 4 MHz

7. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is T_A = 25°C

5. 33.3.2 Supply current characteristics (p.1076 to p.1079)

Incorrect:

33.3.2 Supply current characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions						MIN.	TYP.	MAX.	Unit
Supply current	I_{DD1} Note 1	Operating mode	HS (high-speed main) mode Note 5	f_{HOCO} = 48 MHz Note 3, f_{IH} = 24 MHz Note 3	Basic operation	V_{DD} = 5.0 V			2.0		mA
						V_{DD} = 3.0 V			2.0		mA
					Normal operation	V_{DD} = 5.0 V			3.8	7.0	mA
						V_{DD} = 3.0 V			3.8	7.0	mA
				f_{SUB} = 32.768 kHz Note 4, T_A = +105°C	Normal operation	Square wave input			6.4	35.0	µA
						Resonator connection			6.6	35.0	µA

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. **The values below the MAX. column include the peripheral operation current.** However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator and subsystem clock are stopped.

3. When high-speed system clock and subsystem clock are stopped.

4. When high-speed on-chip oscillator and high-speed system clock are stopped. When setting ultra-low power consumption oscillation (AMPHS1 = 1). **The current flowing into the LCD controller/driver, 16-bit timer KB20, real-time clock 2, 12-bit interval timer, and watchdog timer is not included.**

5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz

2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB} Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

Correct:

33.3.2 Supply current characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current	I_{DD1} Note 1	Operating mode	HS (high-speed main) mode Note 5	f_{HOCO} = 48 MHz Note 3, f_{IH} = 24 MHz Note 3	Basic operation	V_{DD} = 5.0 V		2.0		mA
						V_{DD} = 3.0 V		2.0		mA
					Normal operation	V_{DD} = 5.0 V		3.8	7.0	mA
						V_{DD} = 3.0 V		3.8	7.0	mA
				f_{SUB} = 32.768 kHz Note 4, T_A = +105°C	Normal operation	Square wave input		6.4	35.0	µA
						Resonator connection		6.6	35.0	µA

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The following points apply in the HS (high-speed main) mode.

- The currents in the “TYP.” column do not include the operating currents of the peripheral modules.
- The currents in the “MAX.” column include the operating currents of the peripheral modules, except for those flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, and on-chip pull-up/pull-down resistors, and those flowing while the data flash memory is being rewritten.

In the subsystem clock operation, the currents in both the “TYP.” and “MAX.” columns do not include the operating currents of the peripheral modules. However, in HALT mode, including the current flowing into the real-time clock 2.

2. When high-speed on-chip oscillator and subsystem clock are stopped.

3. When high-speed system clock and subsystem clock are stopped.

4. When high-speed on-chip oscillator and high-speed system clock are stopped. When setting ultra-low power consumption oscillation (AMPHS1 = 1).

5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz

2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB} Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD2} Note 2	HALT mode	HS (high-speed main) mode Note 7	f_{HOCO} = 48 MHz Note 4, f_{IH} = 24 MHz Note 4	V_{DD} = 5.0 V		0.71	2.55	mA
					V_{DD} = 3.0 V		0.71	2.55	mA
				f_{HOCO} = 24 MHz Note 4, f_{IH} = 24 MHz Note 4	V_{DD} = 5.0 V		0.49	1.95	mA
					V_{DD} = 3.0 V		0.49	1.95	mA
				f_{HOCO} = 16 MHz Note 4, f_{IH} = 16 MHz Note 4	V_{DD} = 5.0 V		0.43	1.50	mA
					V_{DD} = 3.0 V		0.43	1.50	mA
			HS (high-speed main) mode Note 7	f_{MX} = 20 MHz Note 3, V_{DD} = 5.0 V	Square wave input		0.31	1.76	mA
					Resonator connection		0.48	1.92	mA
				f_{MX} = 20 MHz Note 3, V_{DD} = 3.0 V	Square wave input		0.29	1.76	mA
					Resonator connection		0.48	1.92	mA
				f_{MX} = 10 MHz Note 3, V_{DD} = 5.0 V	Square wave input		0.20	0.96	mA
					Resonator connection		0.28	1.07	mA
				f_{MX} = 10 MHz Note 3, V_{DD} = 3.0 V	Square wave input		0.19	0.96	mA
					Resonator connection		0.28	1.07	mA
	I_{DD3} Note 6	STOP mode Note 8	T_A = –40°C				0.18	0.52	µA
			T_A = +25°C				0.24	0.52	µA
			T_A = +50°C				0.33	2.21	µA
			T_A = +70°C				0.53	3.94	µA
			T_A = +85°C				0.93	7.95	µA
			T_A = +105°C				2.91	25.00	µA

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. **The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.**

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator and subsystem clock are stopped.

4. When high-speed system clock and subsystem clock are stopped.

5. When high-speed on-chip oscillator and high-speed system clock are stopped.

When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1). **The current flowing into the real-time clock 2 is included. The current flowing into the clock output/buzzer output, 12-bit interval timer, and watchdog timer is not included.**

6. The current flowing into the real-time clock 2, clock output/buzzer output, 12-bit interval timer, and watchdog timer is not included.

7. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz

2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD2} Note 2	HALT mode	HS (high-speed main) mode Note 6	f_{HOCO} = 48 MHz Note 4, f_{IH} = 24 MHz Note 4	V_{DD} = 5.0 V		0.71	2.55	mA
					V_{DD} = 3.0 V		0.71	2.55	mA
				f_{HOCO} = 24 MHz Note 4, f_{IH} = 24 MHz Note 4	V_{DD} = 5.0 V		0.49	1.95	mA
					V_{DD} = 3.0 V		0.49	1.95	mA
				f_{HOCO} = 16 MHz Note 4, f_{IH} = 16 MHz Note 4	V_{DD} = 5.0 V		0.43	1.50	mA
					V_{DD} = 3.0 V		0.43	1.50	mA
			HS (high-speed main) mode Note 6	f_{MX} = 20 MHz Note 3, V_{DD} = 5.0 V	Square wave input		0.31	1.76	mA
					Resonator connection		0.48	1.92	mA
				f_{MX} = 20 MHz Note 3, V_{DD} = 3.0 V	Square wave input		0.29	1.76	mA
					Resonator connection		0.48	1.92	mA
				f_{MX} = 10 MHz Note 3, V_{DD} = 5.0 V	Square wave input		0.20	0.96	mA
					Resonator connection		0.28	1.07	mA
				f_{MX} = 10 MHz Note 3, V_{DD} = 3.0 V	Square wave input		0.19	0.96	mA
					Resonator connection		0.28	1.07	mA
	I_{DD3}	STOP mode Note 7	T_A = –40°C				0.18	0.52	µA
			T_A = +25°C				0.24	0.52	µA
			T_A = +50°C				0.33	2.21	µA
			T_A = +70°C				0.53	3.94	µA
			T_A = +85°C				0.93	7.95	µA
			T_A = +105°C				2.91	25.00	µA

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The following points apply in the HS (high-speed main) mode.

- The currents in the "TYP." column do not include the operating currents of the peripheral modules.
- The currents in the "MAX." column include the operating currents of the peripheral modules, except for those flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, and on-chip pull-up/pull-down resistors, and those flowing while the data flash memory is being rewritten.

In the subsystem clock operation, the currents in both the "TYP." and "MAX." columns do not include the operating currents of the peripheral modules. However, in HALT mode, including the current flowing into the real-time clock 2.

In the STOP mode, the currents in both the "TYP." and "MAX." columns do not include the operating currents of the peripheral modules.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator and subsystem clock are stopped.

4. When high-speed system clock and subsystem clock are stopped.

5. When high-speed on-chip oscillator and high-speed system clock are stopped.

When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1).

8. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is T_A = 25°C

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz

2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz

7. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is T_A = 25°C